1. General description

Trench Maximum Efficiency General Application (MEGA) Schottky barrier rectifier encapsulated in a CFP5 (SOD128) small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 5$ A
- Reverse voltage: $V_R \leq 40$ V
- Low forward voltage
- Low leakage current due to Trench MEGA Schottky technology
- High power capability due to clip-bonding technology
- Small and flat lead SMD power plastic package
- AEC-Q101 qualified

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Freewheeling application
- Reverse polarity protection
- Low power consumption application

4. Quick reference data

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$I_{F(AV)}$</td>
<td>average forward current</td>
<td>$\delta = 0.5$ ; $f = 20$ kHz; $T_{sp} \leq 145$ °C; square wave</td>
<td>-</td>
<td>-</td>
<td>5</td>
<td>A</td>
</tr>
<tr>
<td>$V_R$</td>
<td>reverse voltage</td>
<td>$T_J = 25$ °C</td>
<td>-</td>
<td>-</td>
<td>40</td>
<td>V</td>
</tr>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 5$ A; $t_p \leq 300$ µs; $\delta \leq 0.02$ ; $T_J = 25$ °C</td>
<td>-</td>
<td>470</td>
<td>525</td>
<td>mV</td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 10$ V; $T_J = 25$ °C; pulsed</td>
<td>-</td>
<td>7</td>
<td>24</td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 40$ V; $T_J = 25$ °C; pulsed</td>
<td>-</td>
<td>12</td>
<td>41</td>
<td>µA</td>
</tr>
</tbody>
</table>

[1] Very short pulse, in order to maintain a stable junction temperature.
5. Pinning information

Table 2. Pinning information

<table>
<thead>
<tr>
<th>Pin</th>
<th>Symbol</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
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<tbody>
<tr>
<td>1</td>
<td>K</td>
<td>cathode</td>
<td></td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>A</td>
<td>anode</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

6. Ordering information

Table 3. Ordering information

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Description</th>
<th>Version</th>
</tr>
</thead>
<tbody>
<tr>
<td>PMEG40T50EP</td>
<td>CFP5</td>
<td>plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body</td>
<td>SOD128</td>
</tr>
</tbody>
</table>

7. Marking

Table 4. Marking codes

<table>
<thead>
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<th>Type number</th>
<th>Marking code</th>
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</thead>
<tbody>
<tr>
<td>PMEG40T50EP</td>
<td>DX</td>
</tr>
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</table>
8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>V_R</td>
<td>reverse voltage</td>
<td>T_j = 25 °C</td>
<td>-</td>
<td>40</td>
<td>V</td>
</tr>
<tr>
<td>I_F</td>
<td>forward current</td>
<td>T_sp ≤ 140 °C; δ = 1</td>
<td>-</td>
<td>7</td>
<td>A</td>
</tr>
<tr>
<td>I_FW</td>
<td>average forward current</td>
<td>δ = 0.5 ; f = 20 kHz; T_sp ≤ 145 °C; square wave</td>
<td>-</td>
<td>5</td>
<td>A</td>
</tr>
<tr>
<td>I_FSM</td>
<td>non-repetitive peak</td>
<td>t_p = 8 ms; T_jinit = 25 °C; square wave</td>
<td>-</td>
<td>55</td>
<td>A</td>
</tr>
<tr>
<td>P_tot</td>
<td>total power dissipation</td>
<td>T_amb ≤ 25 °C</td>
<td>[1]</td>
<td>0.75</td>
<td>W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[2]</td>
<td>1.1</td>
<td>W</td>
</tr>
<tr>
<td>T_j</td>
<td>junction temperature</td>
<td>-</td>
<td></td>
<td>175</td>
<td>°C</td>
</tr>
<tr>
<td>T_amb</td>
<td>ambient temperature</td>
<td>-</td>
<td>-55</td>
<td>175</td>
<td>°C</td>
</tr>
<tr>
<td>T_stg</td>
<td>storage temperature</td>
<td>-</td>
<td>-65</td>
<td>175</td>
<td>°C</td>
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</table>


9. Thermal characteristics

Table 6. Thermal characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>R_θ(j-a)</td>
<td>thermal resistance</td>
<td>in free air</td>
<td>[1]</td>
<td>[2]</td>
<td>200</td>
<td>KW</td>
</tr>
<tr>
<td>R_θ(j-sp)</td>
<td>thermal resistance</td>
<td>from junction to solder point</td>
<td>[1]</td>
<td>[3]</td>
<td>130</td>
<td>KW</td>
</tr>
<tr>
<td></td>
<td>from junction to ambient</td>
<td></td>
<td>[4]</td>
<td></td>
<td>12</td>
<td>KW</td>
</tr>
</tbody>
</table>

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values
## 10. Characteristics

Table 7. Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{BR,R}$</td>
<td>reverse breakdown voltage</td>
<td>$I_R = 1 \ mA; T_j = 25 ^\circ C; pulsed</td>
<td>40</td>
<td>-</td>
<td>-</td>
<td>V</td>
</tr>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 0.1 \ A; t_p \leq 300 \ \mu s; \delta \leq 0.02 ; T_j = 25 ^\circ C$</td>
<td>-</td>
<td>290</td>
<td>-</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 1 \ A; t_p \leq 300 \ \mu s; \delta \leq 0.02 ; T_j = 25 ^\circ C$</td>
<td>-</td>
<td>360</td>
<td>410</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 2 \ A; t_p \leq 300 \ \mu s; \delta \leq 0.02 ; T_j = 25 ^\circ C$</td>
<td>-</td>
<td>400</td>
<td>445</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 5 \ A; t_p \leq 300 \ \mu s; \delta \leq 0.02 ; T_j = 25 ^\circ C$</td>
<td>-</td>
<td>470</td>
<td>525</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 5 \ A; t_p \leq 300 \ \mu s; \delta \leq 0.02 ; T_j = -40 ^\circ C$</td>
<td>-</td>
<td>525</td>
<td>-</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 5 \ A; t_p \leq 300 \ \mu s; \delta \leq 0.02 ; T_j = -125 ^\circ C$</td>
<td>-</td>
<td>400</td>
<td>-</td>
<td>mV</td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 10 \ V; T_j = 25 ^\circ C; pulsed</td>
<td>7</td>
<td>24</td>
<td>-</td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 30 \ V; T_j = 25 ^\circ C; pulsed</td>
<td>-</td>
<td>10</td>
<td>-</td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 40 \ V; T_j = 25 ^\circ C; pulsed</td>
<td>-</td>
<td>12</td>
<td>41</td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 40 \ V; T_j = 125 ^\circ C; pulsed</td>
<td>-</td>
<td>8.5</td>
<td>-</td>
<td>mA</td>
</tr>
<tr>
<td>$C_d$</td>
<td>diode capacitance</td>
<td>$V_R = 1 \ V; f = 1 \ MHz; T_j = 25 ^\circ C$</td>
<td>-</td>
<td>820</td>
<td>-</td>
<td>pF</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 10 \ V; f = 1 \ MHz; T_j = 25 ^\circ C$</td>
<td>-</td>
<td>350</td>
<td>-</td>
<td>pF</td>
</tr>
<tr>
<td>$t_{rr}$</td>
<td>reverse recovery time step recovery</td>
<td>$I_F = 0.5 \ A; I_R = 0.5 \ A; I_R(meas) = 0.1 \ A; T_j = 25 ^\circ C$</td>
<td>-</td>
<td>24</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td></td>
<td>reverse recovery time ramp recovery</td>
<td>$dI_F/dt = 200 \ A/\mu s; T_j = 25 ^\circ C; I_F = 6 \ A; V_R = 26 \ V$</td>
<td>-</td>
<td>16</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>$V_{FRM}$</td>
<td>peak forward recovery voltage</td>
<td>$I_F = 0.5 \ A; dV_F/dt = 20 \ A/\mu s; T_j = 25 ^\circ C$</td>
<td>-</td>
<td>378</td>
<td>-</td>
<td>mV</td>
</tr>
</tbody>
</table>

[1] Very short pulse, in order to maintain a stable junction temperature.
Fig. 3. Forward current as a function of forward voltage; typical values

Pulsed condition
1. $T_J = 175 \, ^\circ\text{C}$
2. $T_J = 150 \, ^\circ\text{C}$
3. $T_J = 125 \, ^\circ\text{C}$
4. $T_J = 100 \, ^\circ\text{C}$
5. $T_J = 85 \, ^\circ\text{C}$
6. $T_J = 25 \, ^\circ\text{C}$
7. $T_J = -40 \, ^\circ\text{C}$

Fig. 4. Reverse current as a function of reverse voltage; typical values

Pulsed condition
1. $T_J = 150 \, ^\circ\text{C}$
2. $T_J = 125 \, ^\circ\text{C}$
3. $T_J = 100 \, ^\circ\text{C}$
4. $T_J = 85 \, ^\circ\text{C}$
5. $T_J = 25 \, ^\circ\text{C}$
6. $T_J = -40 \, ^\circ\text{C}$

Fig. 5. Diode capacitance as a function of reverse voltage; typical values

$f = 1 \, \text{MHz}; T_{\text{amb}} = 25 \, ^\circ\text{C}$

Fig. 6. Average forward power dissipation as a function of average forward current; typical values

$T_J = 100 \, ^\circ\text{C}$
1. $\delta = 0.1$
2. $\delta = 0.2$
3. $\delta = 0.5$
4. $\delta = 0.8$
5. $\delta = 1; \text{DC}$
Nexperia

PMEG40T50EP

40 V, 5 A low VF Trench MEGA Schottky barrier rectifier

---

**Fig. 7.** Average reverse power dissipation as a function of reverse voltage; typical values

<table>
<thead>
<tr>
<th>$V_R$ (V)</th>
<th>$P_{R(\text{AV})}$ (W)</th>
</tr>
</thead>
<tbody>
<tr>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>10</td>
<td>0.05</td>
</tr>
<tr>
<td>20</td>
<td>0.1</td>
</tr>
<tr>
<td>30</td>
<td>0.15</td>
</tr>
<tr>
<td>40</td>
<td>0.2</td>
</tr>
</tbody>
</table>

- $T_j = 100 \, ^\circ C$
- (1) $\delta = 1; \text{DC}$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$
- (5) $\delta = 0.2$

**Fig. 8.** Average forward current as a function of ambient temperature; typical values

<table>
<thead>
<tr>
<th>$T_{\text{amb}}$ (°C)</th>
<th>$I_{F(\text{AV})}$ (A)</th>
</tr>
</thead>
<tbody>
<tr>
<td>0</td>
<td>1</td>
</tr>
<tr>
<td>50</td>
<td>2</td>
</tr>
<tr>
<td>100</td>
<td>3</td>
</tr>
<tr>
<td>150</td>
<td>4</td>
</tr>
<tr>
<td>200</td>
<td>5</td>
</tr>
</tbody>
</table>

- FR4 PCB, standard footprint
- $T_j = 175 \, ^\circ C$
- (1) $\delta = 1; \text{DC}$
- (2) $\delta = 0.5; f = 20 \, \text{kHz}$
- (3) $\delta = 0.2; f = 20 \, \text{kHz}$
- (4) $\delta = 0.1; f = 20 \, \text{kHz}$

**Fig. 9.** Average forward current as a function of ambient temperature; typical values

<table>
<thead>
<tr>
<th>$T_{\text{amb}}$ (°C)</th>
<th>$I_{F(\text{AV})}$ (A)</th>
</tr>
</thead>
<tbody>
<tr>
<td>0</td>
<td>1</td>
</tr>
<tr>
<td>50</td>
<td>2</td>
</tr>
<tr>
<td>100</td>
<td>3</td>
</tr>
<tr>
<td>150</td>
<td>4</td>
</tr>
<tr>
<td>200</td>
<td>5</td>
</tr>
</tbody>
</table>

- FR4 PCB, mounting pad for cathode 1 cm$^2$
- $T_j = 175 \, ^\circ C$
- (1) $\delta = 1; \text{DC}$
- (2) $\delta = 0.5; f = 20 \, \text{kHz}$
- (3) $\delta = 0.2; f = 20 \, \text{kHz}$
- (4) $\delta = 0.1; f = 20 \, \text{kHz}$

**Fig. 10.** Average forward current as a function of solder point temperature; typical values

<table>
<thead>
<tr>
<th>$T_{\text{sp}}$ (°C)</th>
<th>$I_{F(\text{AV})}$ (A)</th>
</tr>
</thead>
<tbody>
<tr>
<td>0</td>
<td>1</td>
</tr>
<tr>
<td>50</td>
<td>2</td>
</tr>
<tr>
<td>100</td>
<td>3</td>
</tr>
<tr>
<td>150</td>
<td>4</td>
</tr>
<tr>
<td>200</td>
<td>5</td>
</tr>
</tbody>
</table>

- $T_j = 175 \, ^\circ C$
- (1) $\delta = 1; \text{DC}$
- (2) $\delta = 0.5; f = 20 \, \text{kHz}$
- (3) $\delta = 0.2; f = 20 \, \text{kHz}$
- (4) $\delta = 0.1; f = 20 \, \text{kHz}$

---

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11. Test information

Fig. 11. Reverse recovery definition; step recovery

Fig. 12. Reverse recovery definition; ramp recovery

Fig. 13. Forward recovery definition
The current ratings for the typical waveforms are calculated according to the equations:

\[ I_{F(AV)} = I_M \times \delta \]  
\[ I_{RMS} = I_{F(AV)} \text{ at DC, and } I_{RMS} = I_M \times \sqrt{\delta} \]

with \( I_{RMS} \) defined as RMS current.

**Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

**12. Package outline**

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**Fig. 14. Duty cycle definition**

**Fig. 15. Package outline CFP5 (SOD128)**
13. Soldering

Fig. 16. Reflow soldering footprint for CFP5 (SOD128)
Fig. 17. Wave soldering footprint for CFP5 (SOD128)
14. Revision history

Table 8. Revision history

<table>
<thead>
<tr>
<th>Data sheet ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
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<tbody>
<tr>
<td>PMEG40T50EP v.1</td>
<td>20170809</td>
<td>Product data sheet</td>
<td>-</td>
<td>-</td>
</tr>
</tbody>
</table>
## 15. Legal information

### Data sheet status

<table>
<thead>
<tr>
<th>Document status</th>
<th>Product status</th>
<th>Definition</th>
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</thead>
<tbody>
<tr>
<td>Objective [short] data sheet</td>
<td>Development</td>
<td>This document contains data from the objective specification for product development.</td>
</tr>
<tr>
<td>Preliminary [short] data sheet</td>
<td>Qualification</td>
<td>This document contains data from the preliminary specification.</td>
</tr>
<tr>
<td>Product [short] data sheet</td>
<td>Production</td>
<td>This document contains the product specification.</td>
</tr>
</tbody>
</table>

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term "short data sheet" is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nexperia.com.

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Date of release: 9 August 2017